NSD914F3T5G

High-Speed Switching Diode

The NSD914F3T5G device is a spin-off of our popular SOT-23 three-leaded device. It is designed for high speed switching applications and is housed in the SOT-1123 surface mount package. This device is ideal for low-power surface mount applications where board space is at a premium.

Features

- Reduces Board Space
- This is a Halide-Free Device
- This is a Pb-Free Device

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Reverse Voltage	V_{R}	100	Vdc
Forward Current	lF	200	mAdc
Peak Forward Surge Current	I _{FM(surge)}	500	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation, T _A = 25°C Derate above 25°C	P _D (Note 1)	290 2.3	mW mW/°C
Thermal Resistance, Junction-to-Ambient	R _{θJA} (Note 1)	432	°C/W
Total Device Dissipation, T _A = 25°C Derate above 25°C	P _D (Note 2)	347 2.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient	R _{θJA} (Note 2)	360	°C/W
Thermal Resistance, Junction-to-Lead 3	R _{ΨJL} (Note 2)	143	°C/W
Junction and Storage Temperature Range	T _J , T _{stg}	-55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. 100 mm² 1 oz, copper traces.
- 2. 500 mm² 1 oz, copper traces.



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NSD914F3T5G



SOT-1123 CASE 524AA STYLE 2

MARKING DIAGRAM



R = Device Code M = Date Code

ORDERING INFORMATION

Device	Package	Shipping [†]
NSD914F3T5G	SOT-1123 (Pb-Free)	8000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

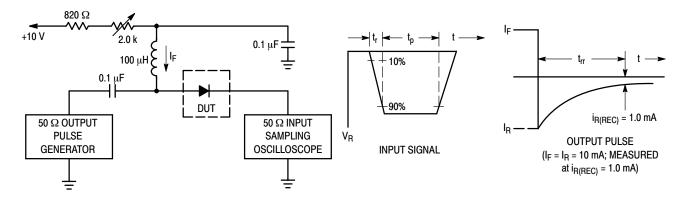
NSD914F3T5G

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS	•				
Reverse Breakdown Voltage (I _R = 100 μAdc)	V _(BR)	100	-	-	Vdc
Reverse Voltage Leakage Current (V _R = 20 Vdc) (V _R = 75 Vdc)	I _R	- -	- -	25 5.0	nAdc μAdc
Diode Capacitance (V _R = 0, f = 1.0 MHz)	C _T	-	-	4.0	pF
Forward Voltage (I _F = 10 mAdc)	V _F	-	-	1.0	Vdc
Reverse Recovery Time (I _F = I _R = 10 mAdc) (Figure 1)	t _{rr}	-	-	4.0	ns

^{1.} FR-5 = $1.0 \times 0.75 \times 0.062$ in. 2. Alumina = $0.4 \times 0.3 \times 0.024$ in. 99.5% alumina.

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Notes: 1. A 2.0 $k\Omega$ variable resistor adjusted for a Forward Current (IF) of 10 mA.

- 2. Input pulse is adjusted so $I_{R(peak)}$ is equal to 10 mA.
- 3. t_p » t_{rr}

Figure 1. Recovery Time Equivalent Test Circuit

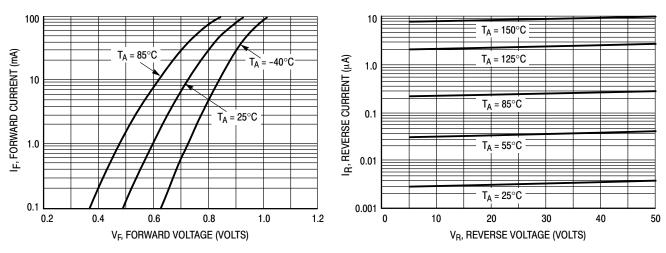


Figure 2. Forward Voltage

Figure 3. Leakage Current

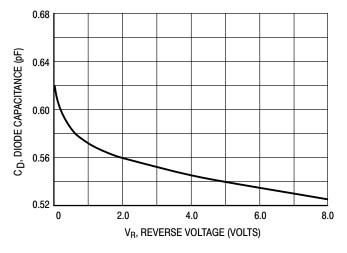


Figure 4. Capacitance

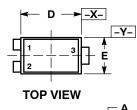


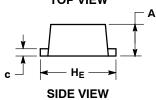


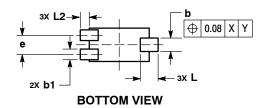
SOT-1123 CASE 524AA ISSUE C

DATE 29 NOV 2011

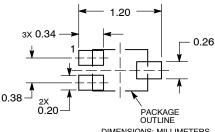
SCALE 8:1







SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: MILLIMETERS.
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE
- MINIMUM THICKNESS OF BASE MATERIAL.
 DIMENSIONS D AND E DO NOT INCLUDE MOLD
 FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.34	0.40	
b	0.15	0.28	
b1	0.10	0.20	
С	0.07	0.17	
D	0.75	0.85	
E	0.55	0.65	
е	0.35	0.40	
HE	0.95	1.05	
L	0.185 REF		
L2	0.05	0.15	

GENERIC MARKING DIAGRAM*



= Specific Device Code Χ

M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking.

Pb-Free indicator, "G" or microdot " ■", may or may not be present.

*For additional information on our Pb-Free strategy and soldering
details, please download the ON Semiconductor Soldering and
Mounting Techniques Reference Manual, SOLDERRM/D.

STYLE 1: PIN 1. BASE 2. EMITTER STYLE 4: PIN 1. CATHODE 2. CATHODE STYLE 5: PIN 1. GATE 2. SOURCE STYLE 2: STYLE 3: PIN 1. ANODE 2. N/C 3. CATHODE PIN 1. ANODE 2. ANODE 3. COLLECTOR 3. CATHODE 3. ANODE 3. DRAIN

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DESCRIPTION:	SOT-1123, 3-LEAD, 1.0X0.6X0.37, 0.35P		PAGE 1 OF 1

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